

## EAST Search History

| Ref # | Hits    | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|---------|---|---|------------------|---------|------------------|
| L1    | 1222337 | (semiconductor die chip dice ic electronic component (integrated adj circuit) flichip (flip adj chip)) with (substrate carrier board ((printed circuit\$2 metal wiring mount\$3) adj4 board)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 06:34 |
| L2    | 62031   | 1 same (flipchip (flip adj chip) ball bump)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 06:33 |
| L3    | 446626  | (bend\$4 flex flexibl\$5 slant groove dip curv\$3 recess\$4) with (substrate carrier board ((printed circuit\$2 metal wiring mount\$3) adj4 board))   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 08:01 |
| L4    | 446626  | 3 same 3  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 06:36 |
| L5    | 7361    | 3 same 2  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 06:36 |
| L6    | 5145    | (module packag\$3) and 5  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 06:37 |
| L7    | 3522    | (metal cuw mo cumo ((copper cu) adj (clad invar mo)) invar) and 6   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 08:02 |
| L8    | 3583    | (metal cuw mo cumo ((copper cu) adj (clad invar mo)) invar steel stainless) and 6   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/06/24 06:38 |

## EAST Search History

|     |       |   |   |    |    |                  |
|-----|-------|---|---|----|----|------------------|
| L9  | 1931  | (organic dielectric) and 8  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/06/24 08:03 |
| L10 | 60884 | cavity with (substrate carrier board<br>((printed circuit\$2 metal wiring<br>mount\$3) adj4 board)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/06/24 08:02 |
| L11 | 2004  | 10 same 2   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/06/24 08:02 |
| L12 | 1858  | 11 not 9  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/06/24 08:02 |
| L13 | 1084  | (metal cuw mo cumo ((copper cu) adj<br>(clad invar mo)) invar) and 12                               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/06/24 08:02 |
| L14 | 488   | (organic dielectric) and 13   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/06/24 08:03 |